| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|-----------|------------------|
| - | 308 | (Dispersion solution slurry) and ('cmp' near5 polishing) and | USPAT; | 2004/09/27 14:26 |
| | | (silica\$2alumina silicon\$2aluminum near2 oxide silicon near2 | US-PGPUB | |
| | | aluminum near2 oxide) | | |
| - | 124 | (Dispersion solution slurry) and polishing and | USPAT; | 2004/09/27 14:22 |
| | | (silica\$2alumina silicon\$2aluminum near2 oxide) | US-PGPUB | |
| - | 50 | (Dispersion solution slurry) and ('cmp' polishing) and | EPO; JPO; | 2004/09/27 16:50 |
| | | (silica\$2alumina silicon\$2aluminum near2 oxide silicon near2 | DERWENT; | |
| | | aluminum near2 oxide) | IBM_TDB | |
| - | 4 | ("5891205" "5382272" "5858813" "5954997").did. | USPAT; | 2004/09/27 14:22 |
| | | , | US-PGPUB | |